



Integrated Device Technology, Inc.
6024 Silver Creek Valley Road, San Jose, CA 95138

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: A0508-01 DATE: 10/10/2005 Product Affected: Green 28L TSOP (PZG28) package Date Effective: 1/9/2006	MEANS OF DISTINGUISHING CHANGED DEVICES: <input type="checkbox"/> Product Mark <input checked="" type="checkbox"/> Back Mark Encrypted "A" prefix on the assembly lot number. Refer to Attachment 2. <input type="checkbox"/> Date Code <input type="checkbox"/> Other
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Contact: Geoffrey Cortes Title: Corporate Quality and Reliability Phone #: (408) 284 8321 Fax #: (408) 284 1450 E-mail: gcortes@idt.com	Attachment:: <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No Samples: Contact the local IDT sales representative
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DESCRIPTION AND PURPOSE OF CHANGE:

<input type="checkbox"/> Die Technology <input type="checkbox"/> Wafer Fabrication Process <input type="checkbox"/> Assembly Process <input type="checkbox"/> Equipment <input type="checkbox"/> Material <input type="checkbox"/> Testing <input checked="" type="checkbox"/> Manufacturing Site <input type="checkbox"/> Data Sheet <input type="checkbox"/> Other	<p>This notification is to advise customers that IDT is transferring the assembly location of the green 28L TSOP (PZG28) from Chippac/Stat-China to OSE-Taiwan. The green 28L TSOP from OSE-Taiwan have a slightly shorter foot length than Chippac/Stat-China.</p> <p>Please refer to the attachment for details.</p>
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RELIABILITY/QUALIFICATION SUMMARY:
Please see PCN attachment for qualification/reliability data.

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____	<input type="checkbox"/> <i>Approval for shipments prior to effective date.</i>
Name/Date: _____	E-Mail Address: _____
Title: _____	Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT 1 - PCN #: A-0508-01

PCN Type: Change in assembly location from Chippac/Stat-China to OSE-Taiwan for green 28L TSOP (PZG28) package.

Data Sheet Change: No

Detail of Change: IDT have completed the qualification to change the assembly location of the green 28L TSOP (PZG28) package from Chippac/Stat-China to OSE-Taiwan. The 28L TSOP from OSE-Taiwan have a slightly shorter foot length. Please refer below for the details. There is no change in the lead tip-to-lead tip length of the package.

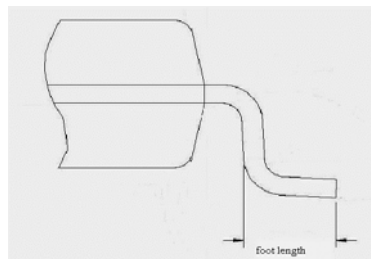
Attachment 3 list details of the qualification results for this changes and Attachment 4 is for the affected devices list.

There is no change to the existing Moisture Sensitive Level (MSL). There is a change to the Datasheet for the foot length dimension as below :-

Description	From	To
Assembly Location	Chippac/Stat-China	OSE-Taiwan
Foot Length range (min - max)	0.5 - 0.7 mm	0.3 - 0.7 mm

Note : Foot length requirement for JEDEC is 0.5 - 0.7 mm.

Illustration of the foot length



Samples are available for selective devices. Please contact your local field sales representative for sample availability and additional information.



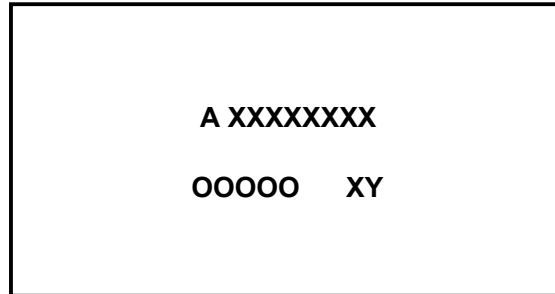
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ATTACHMENT 2 - PCN #: A-0508-01

Illustration of
Encrypted 'A' prefix on the assembly lot number

Example of TSOP-28 Package bottom Mark



A	= OSE-Taiwan built
XXXXXXXX	= Assembly Lot Number
OOOOO	= Country of Origin
XY	= mold date code



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ATTACHMENT 3 - PCN #: A-0508-01

Qualification Plan: P03-07-02

Test Vehicle: IDT71256TT, Green 28L TSOP (PZG28)

Qualification Test Plan and Results:

Description	Test Methods	Sample Size /# Fails	Test Results
Physical Dimensions	JESD22-B100	5/0	5/0 (Pass)
Resistance to Solvents	EIA/JESD22-B107 ; Mil-Std-883 (M 2015)	3/0	3/0 (Pass)
Solderability Test	EIA/JESD22-B102 ; Mil-Std-883 (M 2003)	3/0	3/0 (Pass)
* Steam Pressure Pot Test (SPP), 168hrs	EIA/JESD22-A102	45/0	45/0 (Pass)
Bake and Ball Shear Test	EIA/JESD22-B116	5/0	5/0 (Pass)
Bond pull Test	IDT Spec MAC-3010	5/0	5/0 (Pass)
External Visual Inspection	JESD22-B101	25/0	25/0 (Pass)
Internal Visual Inspection	MIL-STD 883 M-2010	5/0	5/0 (Pass)
X-ray	IDT Spec. MAC-3012	45/0	45/0 (Pass)
Adhesion of Lead Finish	Mil-Std-883 (M 2025)	3/0	3/0 (Pass)
** Moisture Classification Level (MSL 3)	IPC/JEDEC J-STD-20	45/0	45/0 (Pass)
* Highly Accelerated Stress Test (HAST), 100hrs biased	EIA/JESD22-A110	45/0	45/0 (Pass)
Lead Integrity	JESD22-B105	3/0	3/0 (Pass)
* Temperature Cycle (TC), 500cycles (-65°C to 150°C)	JESD22-A104	45/0	45/0 (Pass)

Notes: * Test requires moisture pre-conditioning sequence per JESD22-A113C.

** There was no change to the existing MSL.



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ATTACHMENT 4 - PCN #: A-0508-01

Affected Product List

IDT71V256SA15PZGI	IDT71256SA25PZG
IDT71V256SA15PZG	IDT71256SA20PZGI
IDT71V256SA12PZGI	IDT71256SA20PZG
IDT71V256SA12PZG	IDT71256SA15PZGI
IDT71V256SA10PZGI	IDT71256SA15PZG
IDT71V256SA10PZG	IDT71256SA12PZGI
IDT71256SA25PZGI	IDT71256SA12PZG